

SKM 300GB124D



SEMITRANS™ 3

Low Loss IGBT Modules

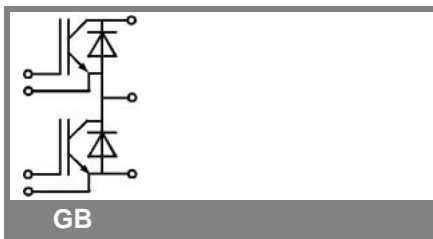
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Features

- MOS input (voltage controlled)
- N channel, homogeneous Si-structure (NPT - Non punch-through IGBT)
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to $6 \times I_{Cnom}$
- Latch-up free
- Fast & soft CAL diodes
- Isolated copper baseplate using DBC Direct copper Bonding Technology
- Large clearance (12 mm) and creepage distances (20 mm)

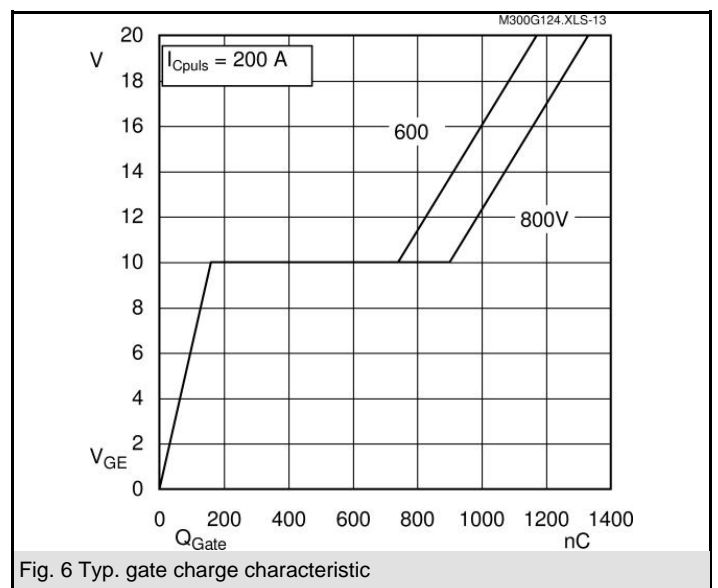
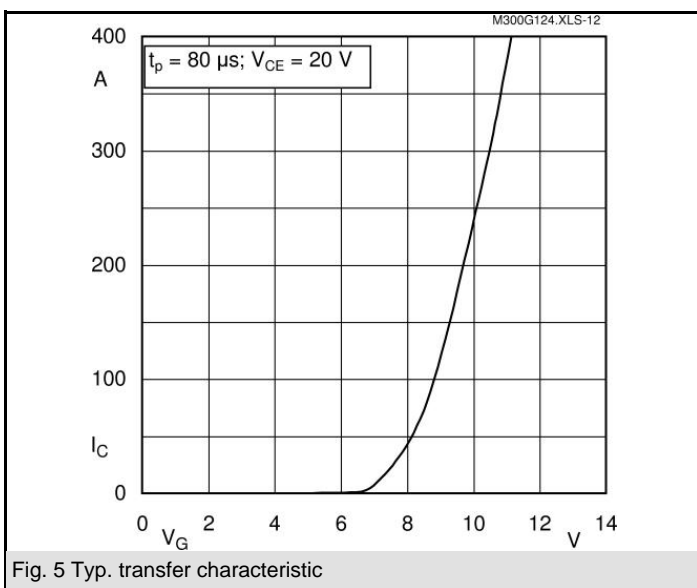
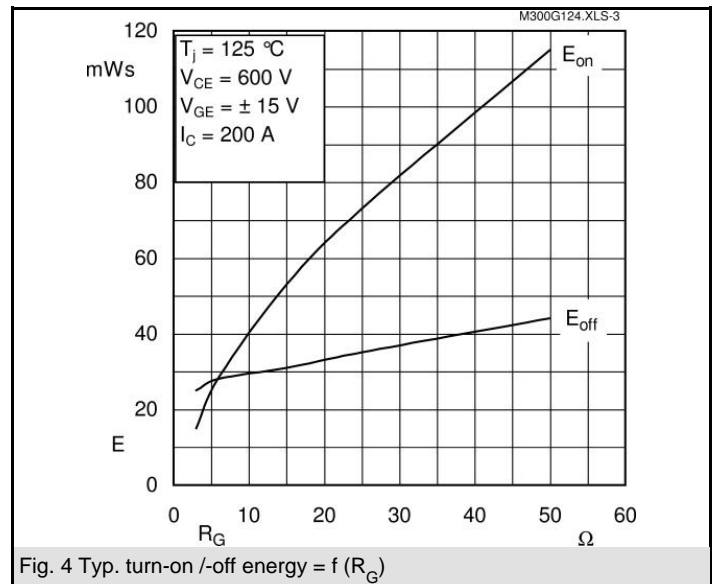
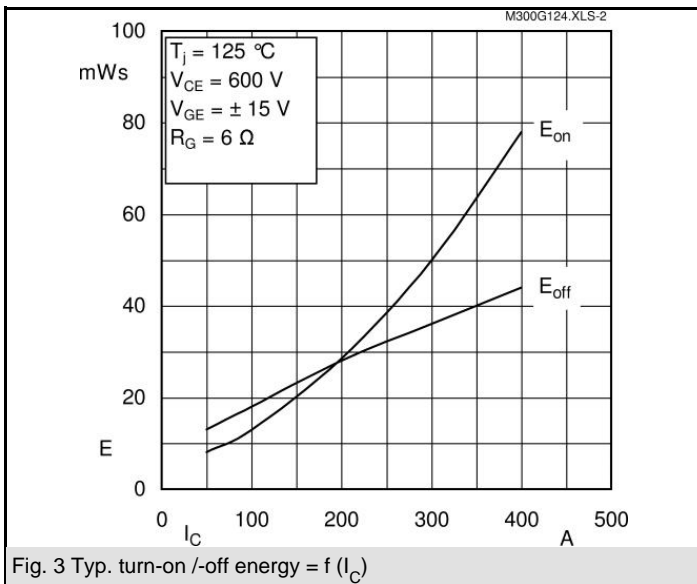
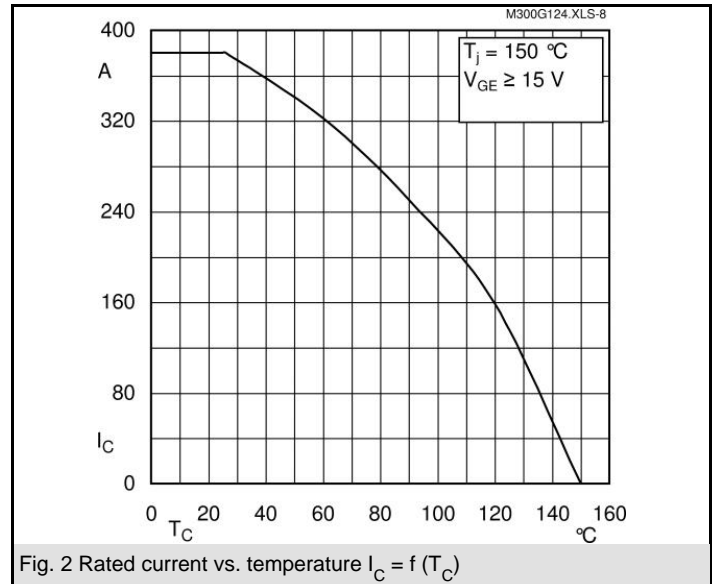
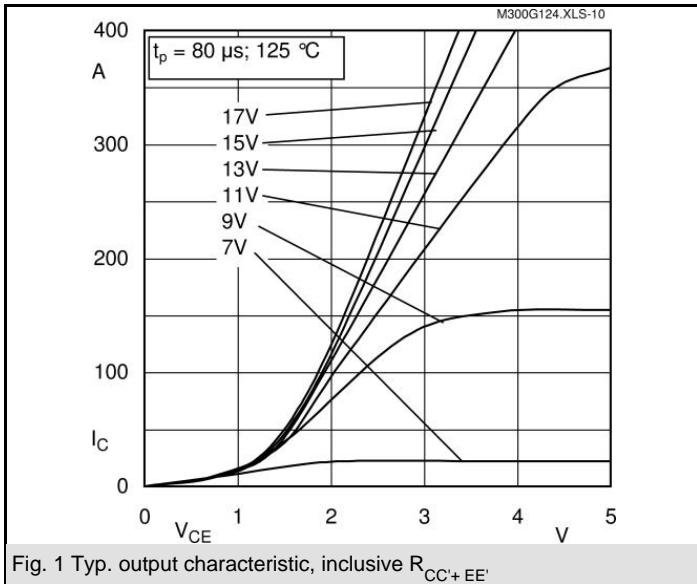
Typical Applications

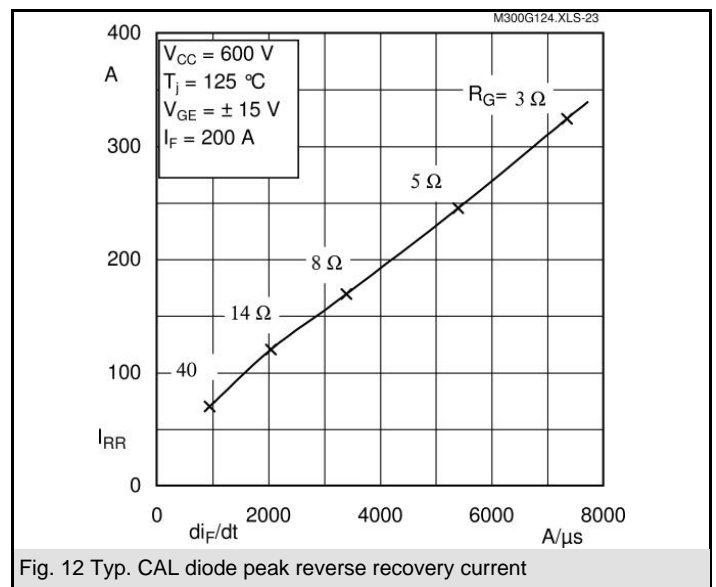
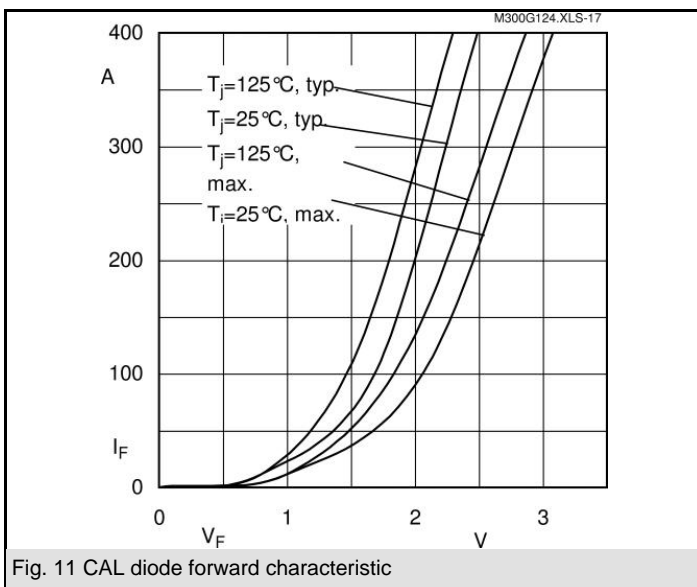
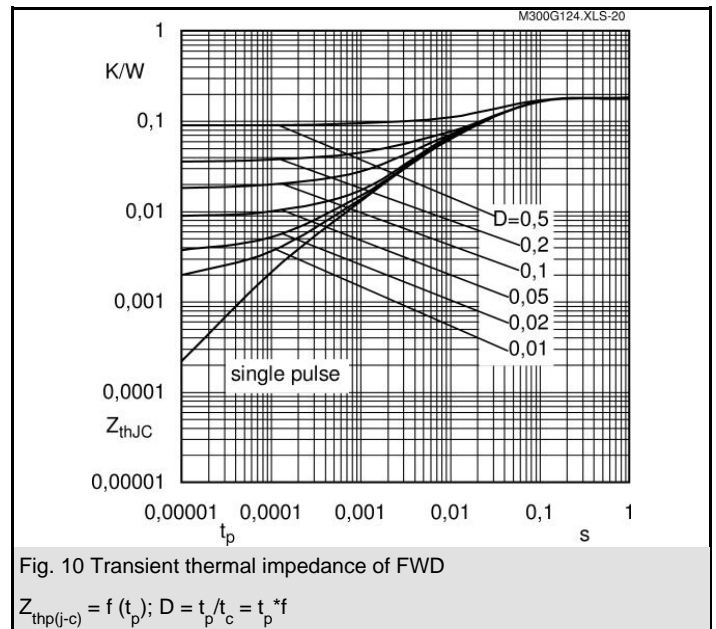
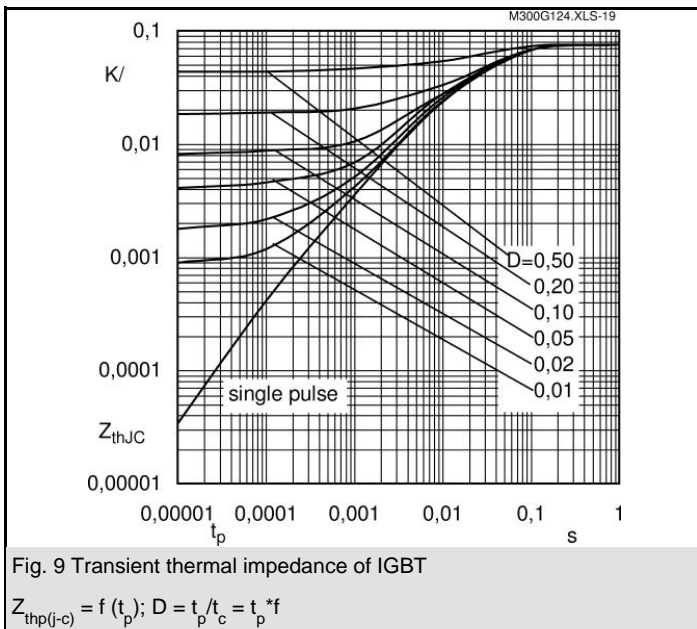
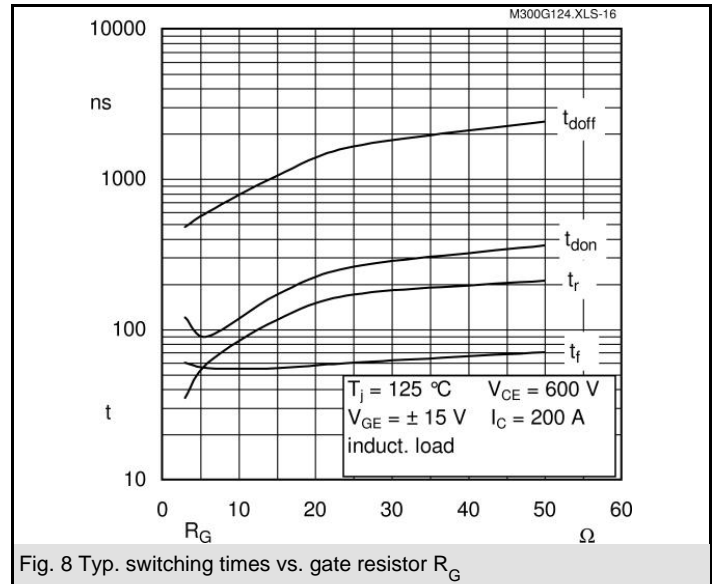
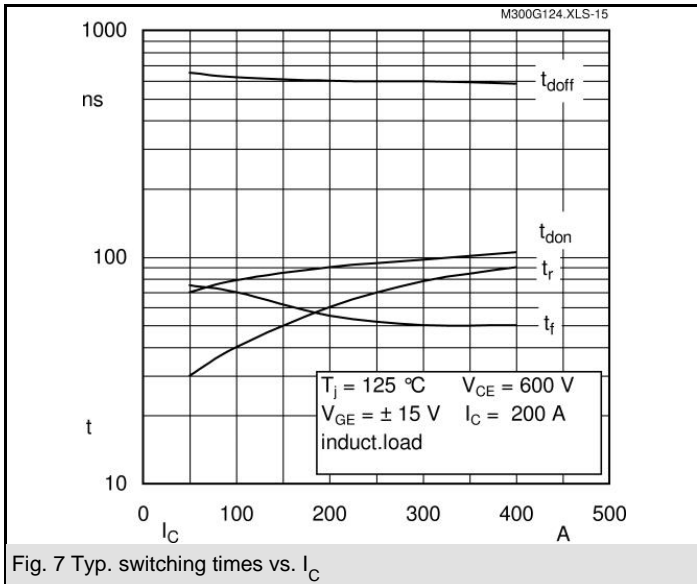
- Switching (not for linear use)
- AC inverter drives
- UPS



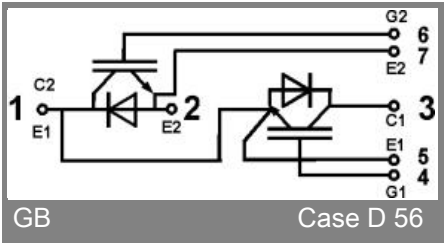
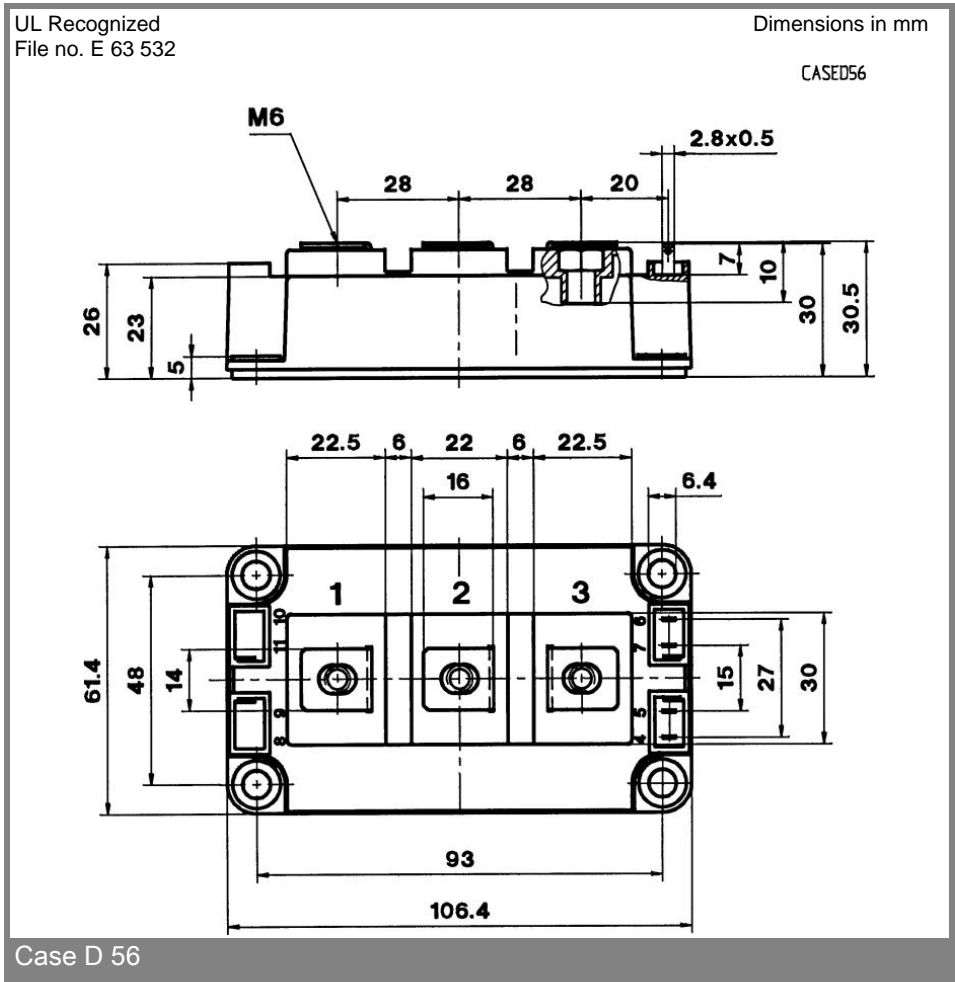
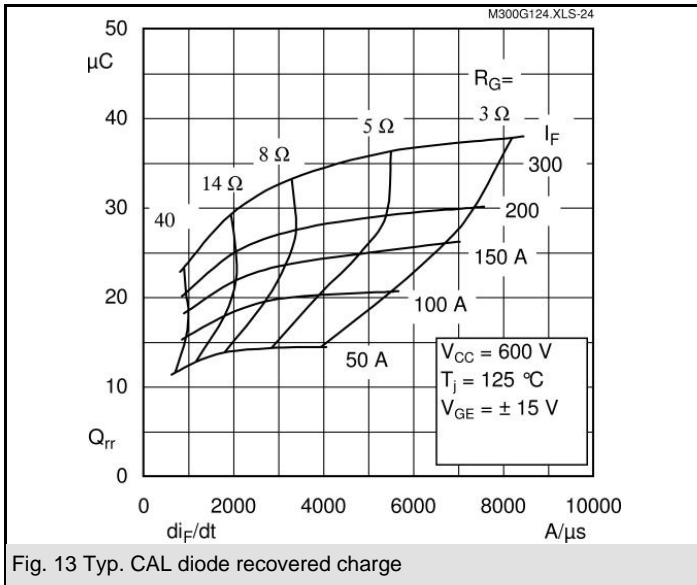
Absolute Maximum Ratings		$T_c = 25\text{ }^\circ\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
IGBT			
V_{CES}		1200	V
I_C	$T_c = 25\text{ (65)}\text{ }^\circ\text{C}$	380 (300)	A
I_{CRM}	$t_p = 1\text{ ms}$	400	A
V_{GES}		± 20	V
T_{vj} (T_{stg})	$T_{OPERATION} \leq T_{stg}$	- 40 ... + 150 (125)	$^\circ\text{C}$
V_{isol}	AC, 1 min.	2500	V
Inverse diode			
I_F	$T_c = 25\text{ (80)}\text{ }^\circ\text{C}$	260 (180)	A
I_{FRM}	$t_p = 1\text{ ms}$	400	A
I_{FSM}	$t_p = 10\text{ ms}$; sin.; $T_j = 150\text{ }^\circ\text{C}$	2200	A

Characteristics		$T_c = 25\text{ }^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}$; $I_C = 8\text{ mA}$	4,5	5,5	6,5	V
I_{CES}	$V_{GE} = 0$; $V_{CE} = V_{CES}$; $T_j = 25\text{ (125)}\text{ }^\circ\text{C}$		0,2	0,6	mA
$V_{CE(TO)}$	$T_j = 25\text{ (125)}\text{ }^\circ\text{C}$		1,1 (1,1)	1,25 (1,25)	V
r_{CE}	$V_{GE} = 15\text{ V}$; $T_j = 25\text{ (125)}\text{ }^\circ\text{C}$		5 (6,5)	6 (8)	m Ω
$V_{CE(sat)}$	$I_{Cnom} = 200\text{ A}$; $V_{GE} = 15\text{ V}$; chip level		2,1 (2,4)	2,45 (2,85)	V
C_{ies}	under following conditions		13		nF
C_{oes}	$V_{GE} = 0$; $V_{CE} = 25\text{ V}$; $f = 1\text{ MHz}$		2		nF
C_{res}			1	1,3	nF
L_{CE}				20	nH
$R_{CC'+EE'}$	res.; terminal-chip $T_c = 25\text{ (125)}\text{ }^\circ\text{C}$		0,35 (0,5)		m Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$; $I_{Cnom} = 200\text{ A}$		90		ns
t_r	$R_{Gon} = R_{Goff} = 6\text{ }^\circ\Omega$; $T_j = 125\text{ }^\circ\text{C}$		60		ns
$t_{d(off)}$	$V_{GE} = \pm 15\text{ V}$		600		ns
t_f			55		ns
$E_{on} (E_{off})$			29 (28)		mJ
Inverse diode					
$V_F = V_{EC}$	$I_{Fnom} = 200\text{ A}$; $V_{GE} = 0\text{ V}$; $T_j = 25\text{ (125)}\text{ }^\circ\text{C}$		2 (1,8)	2,5	V
$V_{(TO)}$	$T_j = 125\text{ () }^\circ\text{C}$		1,1	1,2	V
r_T	$T_j = 125\text{ () }^\circ\text{C}$			5,5	m Ω
I_{RRM}	$I_{Fnom} = 200\text{ A}$; $T_j = 125\text{ () }^\circ\text{C}$		120		A
Q_{rr}	$di/dt = A/\mu\text{s}$		25		μC
E_{rr}	$V_{GE} = V$				mJ
Thermal characteristics					
$R_{th(j-c)}$	per IGBT			0,075	K/W
$R_{th(j-c)D}$	per Inverse Diode			0,18	K/W
$R_{th(c-s)}$	per module			0,038	K/W
Mechanical data					
M_s	to heatsink M6	3		5	Nm
M_t	to terminals M6				Nm
w				325	g





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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.